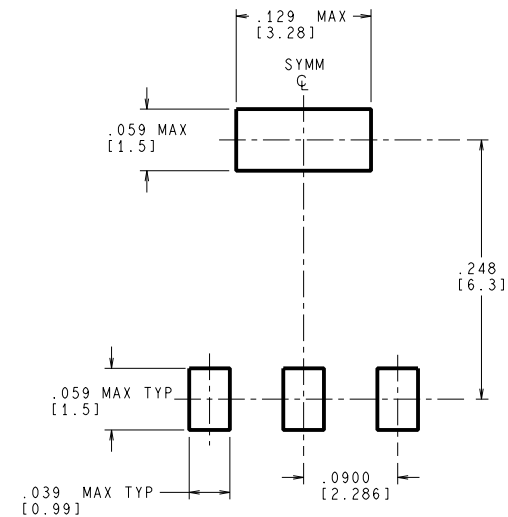
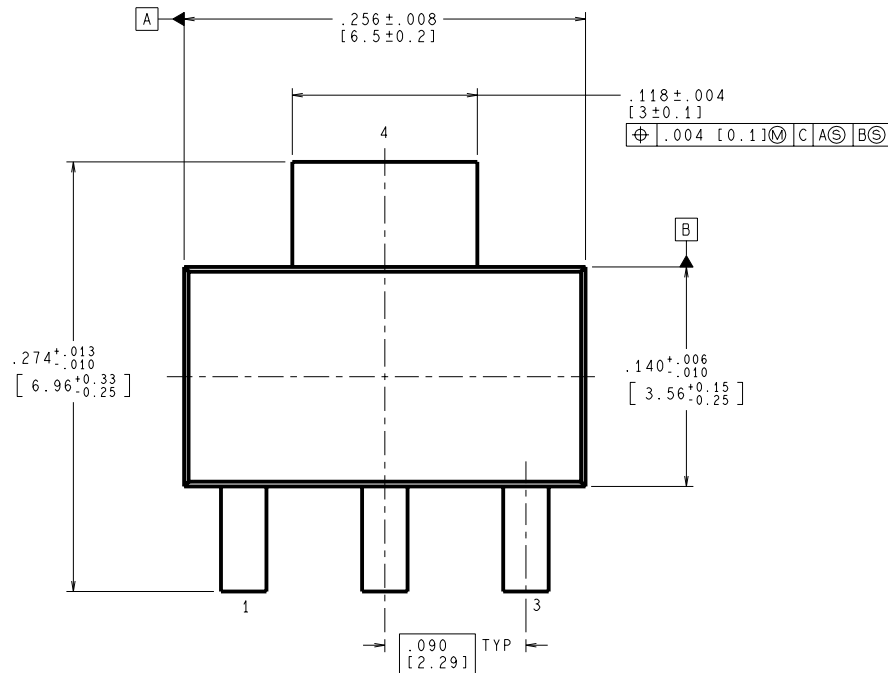
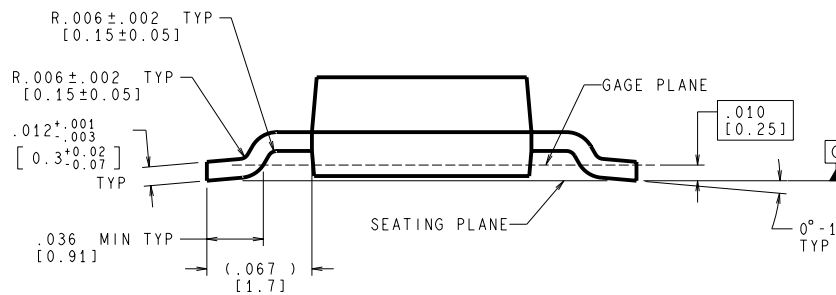
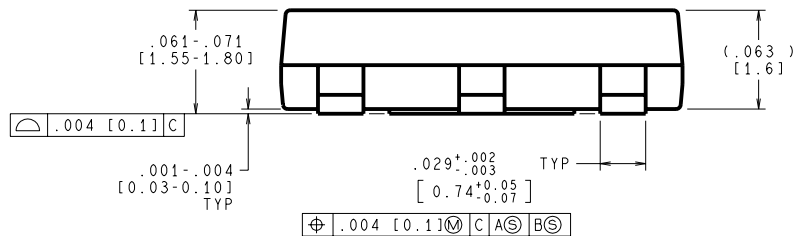


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11176	01/25/96	TL/OM
B	COPLANARITY .004(0.1) WAS .003(0.07); NOTE 1: 200 WAS 150; 5.08 WAS 3.81; UPDATE DATUMS TO CURRENT STD.	11928	02/23/1998	MS/



LAND PATTERN RECOMMENDATION



CONTROLLING DIMENSION IS INCH
VALUES IN () ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH TO BE 200 MICROINCHES/ 5.08 MICROMETERS
MINIMUM TIN/LEAD (SOLDER) ON COPPER.
- REFERENCE JEDEC REGISTRATION TO-261, VARIATION AA, ISSUE A, DATED JAN 1990.

APPROVALS		DATE		 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN: T. LEQUANG		01/25/96			
DFTG. CHK.					
ENGR. CHK.					
 INCH (MM)				MOLDED PACKAGE, SOT-223, 4 LEAD	
SCALE: N/A		SIZE: C		DRAWING NUMBER: (SC)MKT-MA04A	
DO NOT SCALE DRAWING		REV: B		SHEET 1 of 1	